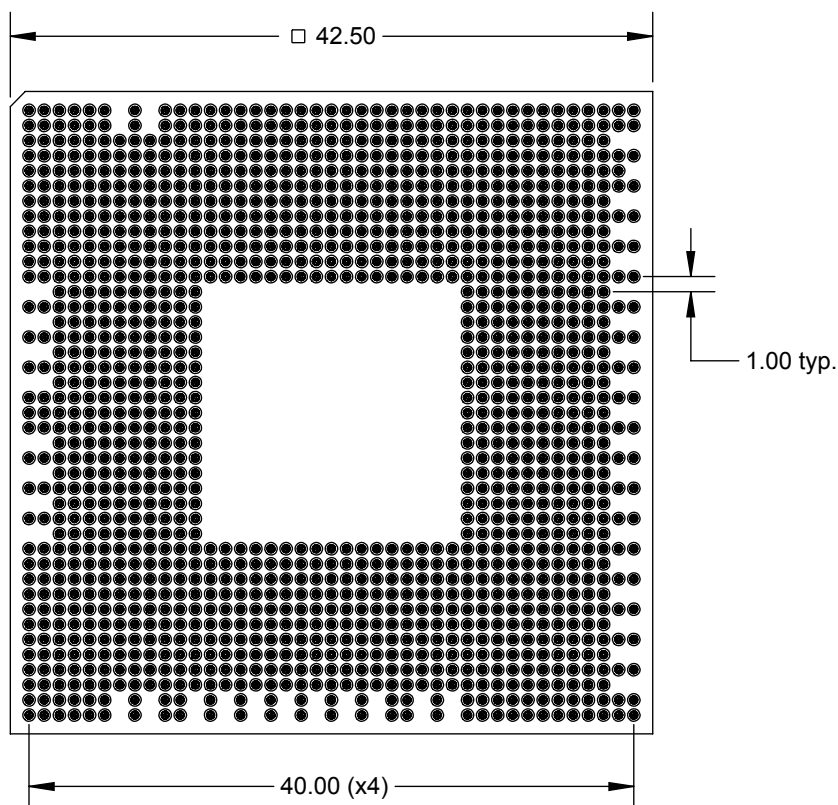
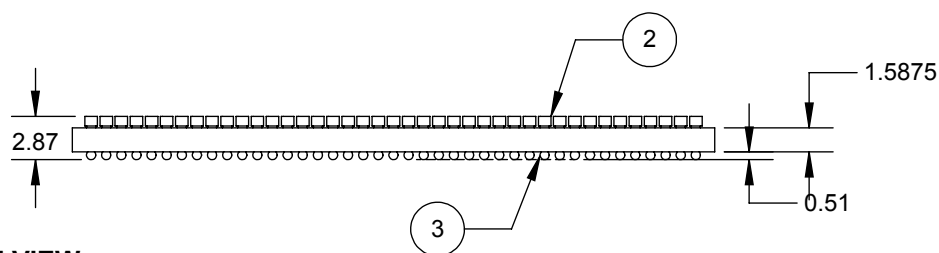


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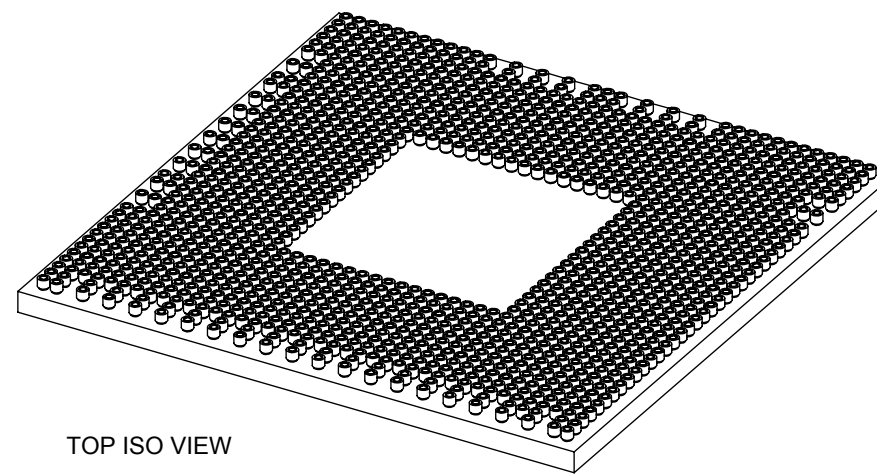
ITEM NO.	DESCRIPTION	Material
1	SF Pin Substrate	FR4 High temp
2	P-S519A, Socket Pin, 1.0mm centers minimum, #4 clip	Body - Gold Plated Brass 360, Clip - Gold plated Beryllium Copper 172
3	Solder Ball, ROHS Compliant 0.024" Dia	Sn96.5 Ag3.0 Cu0.5



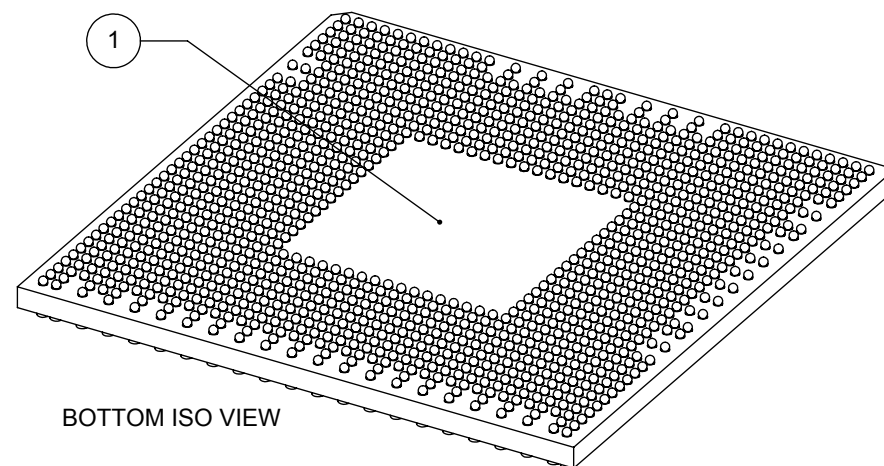
TOP VIEW



SIDE VIEW



TOP ISO VIEW



BOTTOM ISO VIEW

Description: SF-BGA 42.5mm 41x41 array 1mm pitch

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [± 0.001 "], Pitches (from true position) $\pm 0.025\text{mm}$ [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p>Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	<p>Material: N/A Finish: N/A Weight: 8.17</p>	STATUS: Released	SHEET: 1 OF 1	REV. A
		ENG: E. Smolentseva	DRAWN BY: M. Raske	SCALE: 2:1
		FILE: SF-BGA1309A-B-42F Dwg	DATE: 04/16/2015	